



# BC846BMB

65 V, 100 mA NPN general-purpose transistor

Rev. 1 — 15 May 2012

Product data sheet

## 1. Product profile

### 1.1 General description

NPN general-purpose transistor in a leadless ultra small DFN1006B-3 (SOT883B) Surface-Mounted Device (SMD) plastic package.

### 1.2 Features and benefits

- Leadless ultra small SMD plastic package
- Low package height of 0.37 mm
- Power dissipation comparable to SOT23
- AEC-Q101 qualified

### 1.3 Applications

- General-purpose switching and amplification
- Mobile applications

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CE0}$	collector-emitter voltage	open base	-	-	65	V
$I_C$	collector current		-	-	100	mA
$h_{FE}$	DC current gain	$V_{CE} = 5\text{ V};$ $I_C = 2\text{ mA}$	200	-	450	

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	base	<p>Transparent top view</p>	<p>sym021</p>
2	emitter		
3	collector		



### 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BC846BMB	DFN1006B-3	leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.37 mm	SOT883B

### 4. Marking

Table 4. Marking codes

Type number	Marking code
BC846BMB	0100 1011

#### 4.1 Binary marking code description

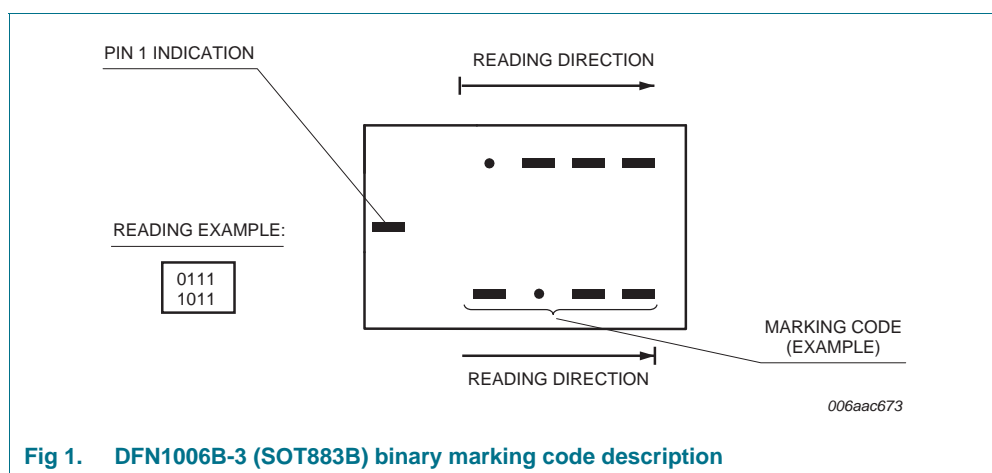


Fig 1. DFN1006B-3 (SOT883B) binary marking code description

## 5. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	80	V
$V_{CEO}$	collector-emitter voltage	open base	-	65	V
$V_{EBO}$	emitter-base voltage	open collector	-	6	V
$I_C$	collector current		-	100	mA
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	200	mA
$I_{BM}$	peak base current	single pulse; $t_p \leq 1$ ms	-	200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	[1]	250	mW
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

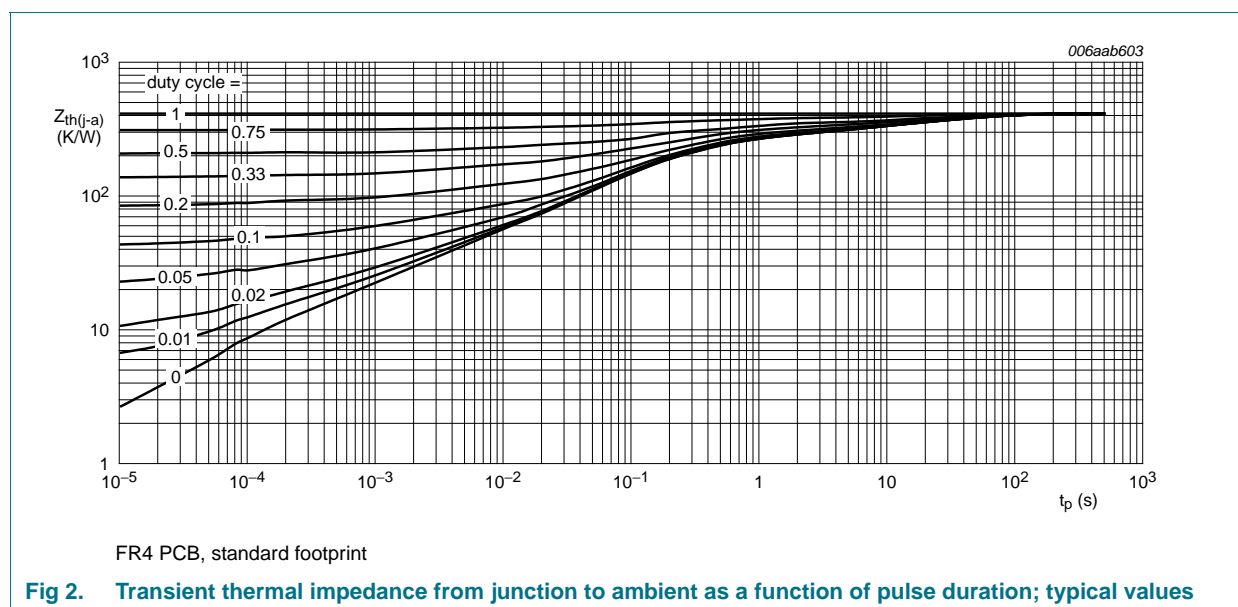
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	500	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.



## 7. Characteristics

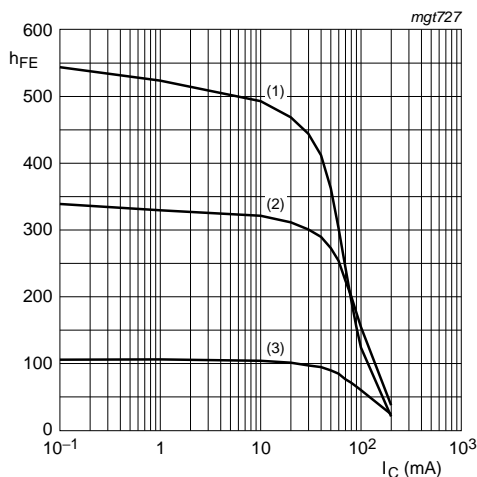
**Table 7. Characteristics**
 $T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{CBO}$	collector-base cut-off current	$V_{CB} = 30\text{ V}; I_E = 0\text{ A}$	-	-	15	nA
		$V_{CB} = 30\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	5	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_E = 0\text{ A}$	-	-	100	nA
$h_{FE}$	DC current gain	$V_{CE} = 5\text{ V}; I_C = 2\text{ mA}$	200	-	450	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	-	90	200	mV
		$I_C = 100\text{ mA}; I_B = 5\text{ mA}$	[1] -	200	400	mV
$V_{BEsat}$	base-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	[2] -	760	-	mV
		$I_C = 100\text{ mA}; I_B = 5\text{ mA}$	[2] -	900	-	mV
$V_{BE}$	base-emitter voltage	$I_C = 2\text{ mA}; V_{CE} = 5\text{ V}$	[3] 580	660	700	mV
		$I_C = 10\text{ mA}; V_{CE} = 5\text{ V}$	[3] -	-	770	mV
$f_T$	transition frequency	$V_{CE} = 5\text{ V}; I_C = 10\text{ mA}; f = 100\text{ MHz}$	100	-	-	MHz
$C_c$	collector capacitance	$V_{CB} = 10\text{ V}; I_E = i_e = 0\text{ A}; f = 1\text{ MHz}$	-	2	3	pF
$C_e$	emitter capacitance	$V_{EB} = 0.5\text{ V}; I_C = i_c = 0\text{ A}; f = 1\text{ MHz}$	-	11	-	pF
NF	noise figure	$I_C = 200\text{ }\mu\text{A}; V_{CE} = 5\text{ V}; R_S = 2\text{ k}\Omega; f = 1\text{ kHz}; B = 200\text{ Hz}$	-	2	10	dB

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .

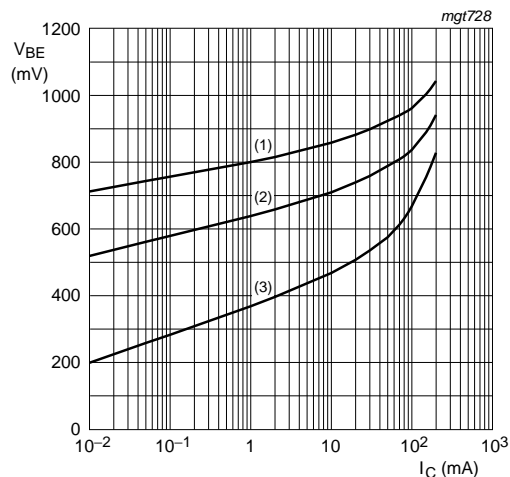
[2]  $V_{BEsat}$  decreases by approximately 1.7 mV/K with increasing temperature.

[3]  $V_{BE}$  decreases by approximately 2 mV/K with increasing temperature.



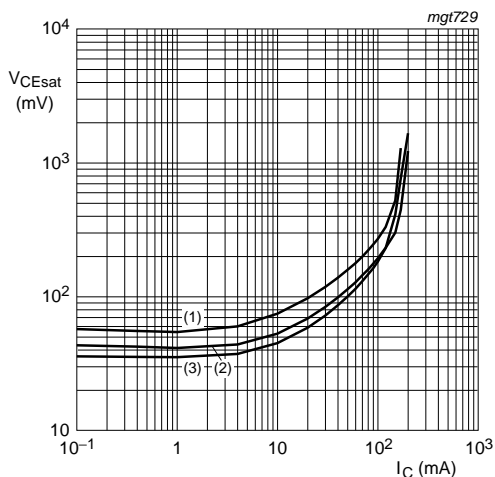
- $V_{CE} = 5 \text{ V}$   
 (1)  $T_{amb} = 150 \text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = -55 \text{ }^{\circ}\text{C}$

**Fig 3. DC current gain as a function of collector current; typical values**



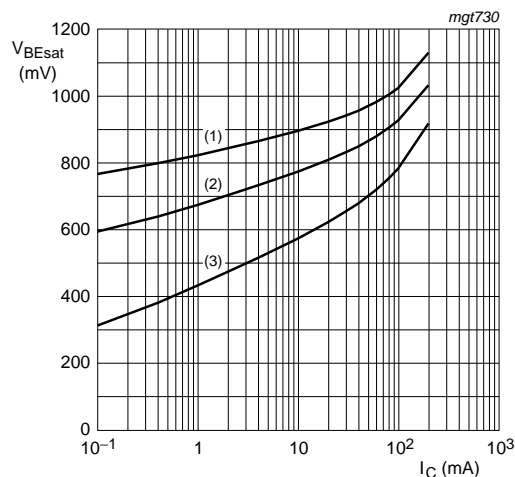
- $V_{CE} = 5 \text{ V}$   
 (1)  $T_{amb} = -55 \text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = 150 \text{ }^{\circ}\text{C}$

**Fig 4. Base-emitter voltage as a function of collector current; typical values**



- $I_C/I_B = 20$   
 (1)  $T_{amb} = 150 \text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = -55 \text{ }^{\circ}\text{C}$

**Fig 5. Collector-emitter saturation voltage as a function of collector current; typical values**



- $I_C/I_B = 10$   
 (1)  $T_{amb} = -55 \text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = 150 \text{ }^{\circ}\text{C}$

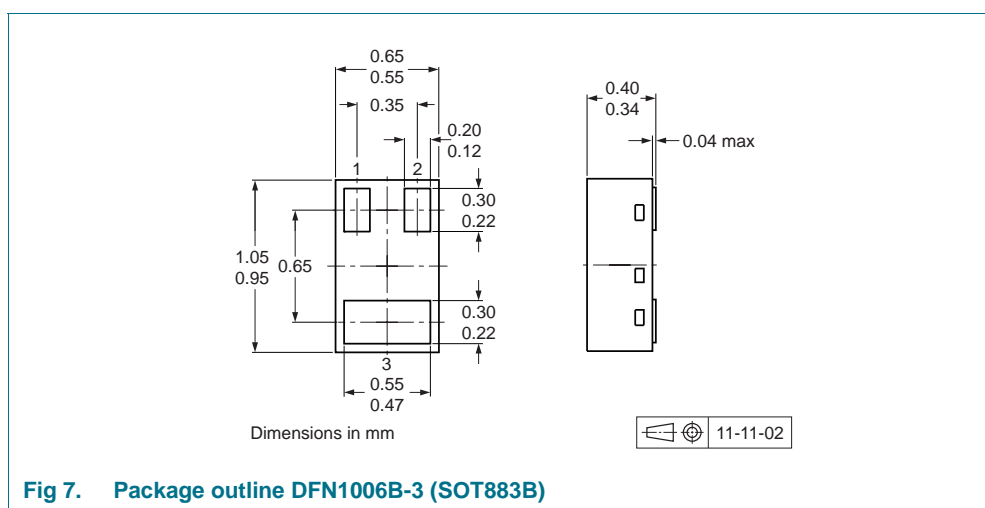
**Fig 6. Base-emitter saturation voltage as a function of collector current; typical values**

## 8. Test information

## 9. Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 10. Package outline



## 11. Packing information

**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

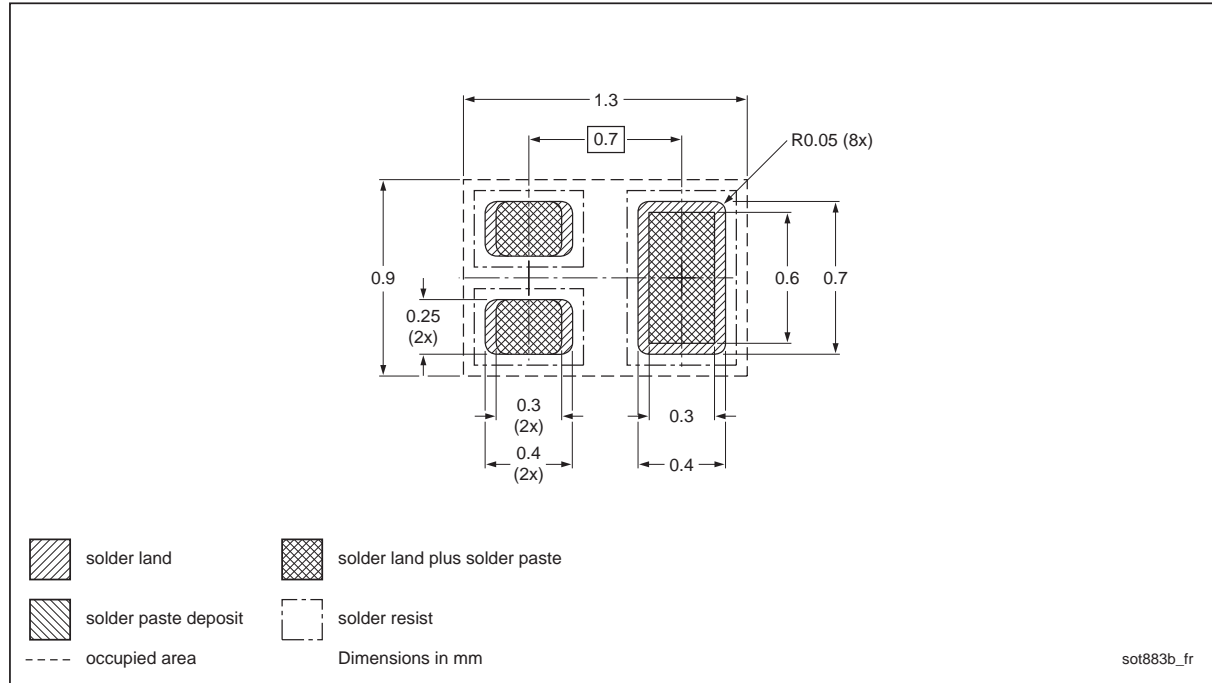
Type number	Package	Description	Packing quantity
			10000
BC846BMB	SOT883B	2 mm pitch, 8 mm tape and reel	-315

[1] For further information and the availability of packing methods, see [Section 15](#).

## 12. Soldering

Footprint information for reflow soldering

SOT883B



**Fig 8. Reflow soldering footprint DFN1006B-3 (SOT883B)**

## 13. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BC846BMB v.1	20120515	Product data sheet	-	-

## 14. Legal information

### 14.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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[2] The term 'short data sheet' is explained in section "Definitions".

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